

MOS FIELD EFFECT TRANSISTOR μ PA1811

P-CHANNEL MOS FIELD EFFECT TRANSISTOR **FOR SWITCHING**

DESCRIPTION

The μ PA1811 is a switching device which can be driven directly by a 2.5-V power source.

The μ PA1811 features a low on-state resistance and excellent switching characteristics, and is suitable for applications such as power switch of portable machine and so on.

FEATURES

- Can be driven by a 2.5- V power source
- · Low on-state resistance

RDS(on)1 = 75 m Ω MAX. (VGS = -4.5 V, ID = -2.0 A)

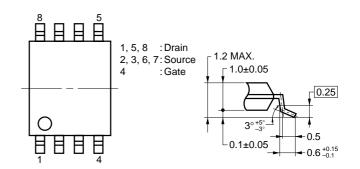
 $R_{DS(on)2} = 80 \text{ m}\Omega$ MAX. (Vgs = -4.0 V, ID = -2.0 A)

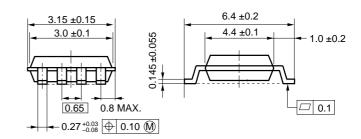
RDS(on)3 = 120 m Ω MAX. (VGS = -2.5 V, ID = -2.0 A)

ORDERING INFORMATION

PART NUMBER	PACKAGE
μPA1811GR-9JG	Power TSSOP8

PACKAGE DRAWING (Unit: mm)

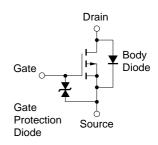




ABSOLUTE MAXIMUM RATINGS ($T_A = 25$ °C)

Drain to Source Voltage	VDSS	-20	V
Gate to Source Voltage	Vgss	-12/+6	V
Drain Current (DC)	I _{D(DC)}	±4.0	Α
Drain Current (pulse) Note1	D(pulse)	±16	Α
Total Power Dissipation Note2	Рт	2.0	W
Channel Temperature	Tch	150	°C
Storage Temperature	T_{stg}	-55 to +150	°C
	Gate to Source Voltage Drain Current (DC) Drain Current (pulse) Note1 Total Power Dissipation Note2 Channel Temperature	Gate to Source Voltage Drain Current (DC) Drain Current (pulse) Note1 Total Power Dissipation Note2 Channel Temperature VGSS ID(DC) ID(pulse) PT Tch	Gate to Source Voltage Vgss -12/+6 Drain Current (DC) Drain Current (pulse) Note1 Total Power Dissipation Note2 Channel Temperature Vgss -12/+6 LD(DC) ±4.0 LD(pulse) ±16 Total Power Dissipation Note2 PT 2.0 Tch 150

EQUIVALENT CIRCUIT



Notes 1. PW \leq 10 μ s, Duty Cycle \leq 1 %

2. Mounted on ceramic substrate of 5000 mm² x 1.1 mm

Remark

The diode connected between the gate and source of the transistor serves as a protector against ESD. When this device actually used, an additional protection circuit is externally required if a voltage exceeding the rated voltage may be applied to this device.

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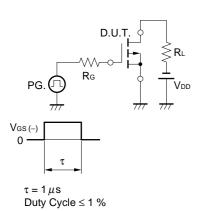
Not all devices/types available in every country. Please check with local NEC representative for availability and additional information.

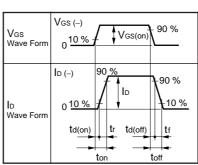


ELECTRICAL CHARACTERISTICS (TA = 25 °C)

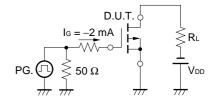
CHARACTERISTICS	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Zero Gate Voltage Drain Current	IDSS	Vps = -20 V, Vgs = 0 V			-10	μΑ
Gate Leakage Current	Igss	Vgs = ±12 V, Vps = 0 V			±10	μΑ
Gate Cut-off Voltage	V _{GS(off)}	V _{DS} = -10 V, I _D = -1 mA	-0.5	-0.9	-1.5	٧
Forward Transfer Admittance	yfs	V _{DS} = -10 V, I _D = -2.0 A	2.5	6.8		S
Drain to Source On-state Resistance	RDS(on)1	V _G S = -4.5 V, I _D = -2.0 A		42	75	mΩ
	RDS(on)2	V _G S = -4.0 V, I _D = -2.0 A		46	80	mΩ
	R _{DS(on)3}	Vgs = -2.5 V, ID = -2.0 A		73	120	mΩ
Input Capacitance	Ciss	V _{DS} = -10 V		1160		pF
Output Capacitance	Coss	V _G S = 0 V		680		pF
Reverse Transfer Capacitance	Crss	f = 1 MHz		210		pF
Turn-on Delay Time	td(on)	V _{DD} = -10 V		40		ns
Rise Time	tr	I _D = -2.0 A		100		ns
Turn-off Delay Time	td(off)	$V_{GS(on)} = -4.0 \text{ V}$		90		ns
Fall Time	tf	$R_G = 5 \Omega$		60		ns
Total Gate Charge	Q _G	V _{DD} = −10 V		36		nC
Gate to Source Charge	Qgs	ID = -4.0 A		5		nC
Gate to Drain Charge	Q _{GD}	Vgs = -4.0 V		16		nC
Diode Forward Voltage	V _F (S-D)	IF = 4.0 A, VGS = 0 V		0.74		V
Reverse Recovery Time	trr	IF = 4.0 A, VGS = 0 V		77		ns
Reverse Recovery Charge	Qrr	di/dt = 100 A/μS		69		nC

TEST CIRCUIT 1 SWITCHING TIME



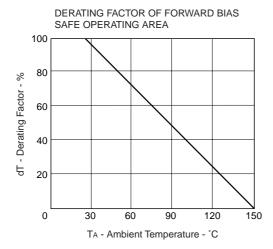


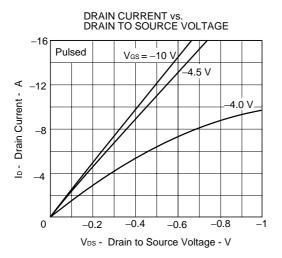
TEST CIRCUIT 2 GATE CHARGE

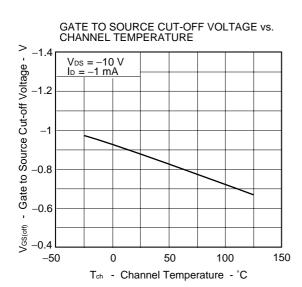


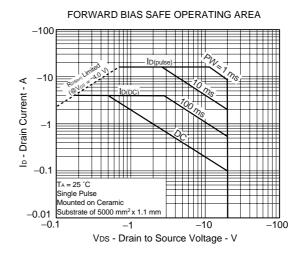


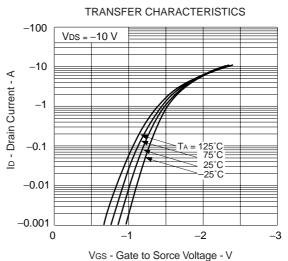
★ TYPICAL CHARACTERISTICS (T_A = 25 °C)

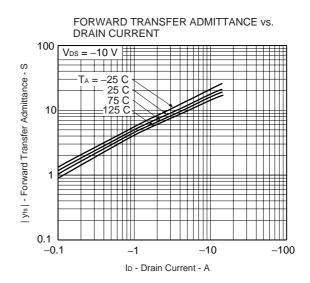


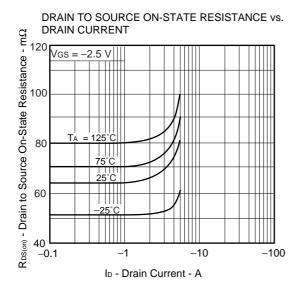


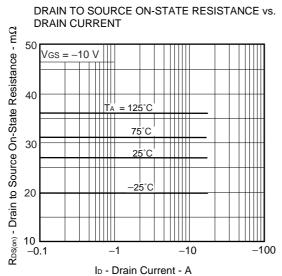


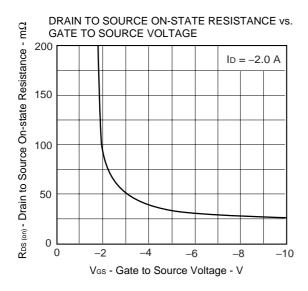


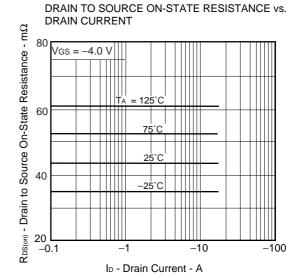


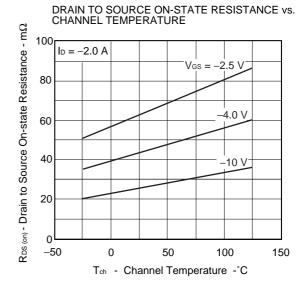


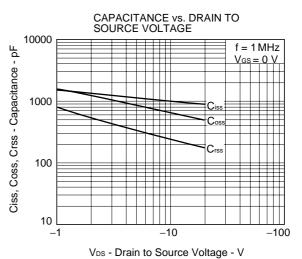




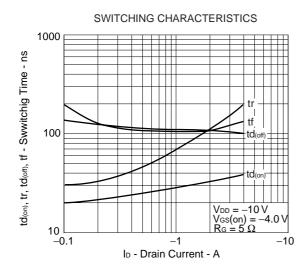




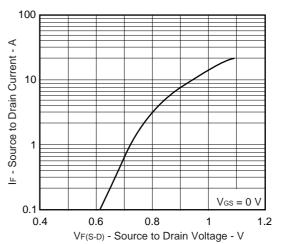


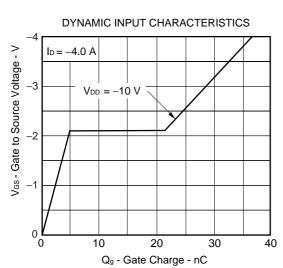




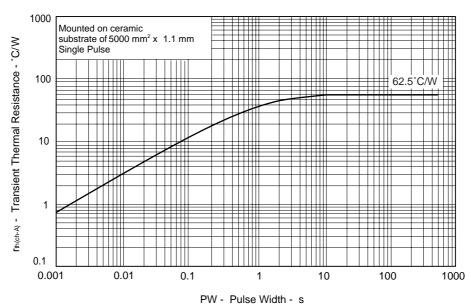


SOURCE TO DRAIN DIODE FORWARD VOLTAGE





TRANSIENT THERMAL RESISTANCE vs. PULSE WIDTH



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[MEMO]

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